

## **IN THE SPECIFICATION**

*Please amend the title as follows:*

**--ELECTRICALLY CONDUCTIVE PASTES--**

*Please amend the paragraph on page 2 at line 19 as follows:*

**--Patent Reference 2: Japanese Patent No. 2941002--**

*Please amend the paragraph on page 15 at line 14 as follows:*

**--An organic vehicle solution having a resin content of 14 wt% was prepared by dissolving ethyl cellulose having a molecular weight of 13,500 in  $\alpha$ -terpineol. A silver powder having a type and amount shown in Tables II and III was added as a metal powder to the solution, and the resulting solution was mixed thoroughly using a rotary agitating deaerator. A glass frit having a type and amount shown in Tables II and III was further added to the solution, with stirring being continued. After visual confirmation of the uniformity, the solution was applied to a three-roll mill in order to prepare a conductive paste. The resulting conductive pastes in all Examples 7 to 13 and Comparative Examples [[1]] 4 and [[2]] 6 did not have poor appearance in an ordinary state.--**

*Please amend the paragraph on page 20 at line 1 as follows:*

**--As shown in Tables II and III, the samples that were prepared at a sintering temperature of 500°C exhibited a volume resistivity of  $3\mu\Omega \bullet \text{cm}$  or less in all Examples 7 to 13 and Comparative Examples [[2]] 5 and 6, exhibiting high conductivity. However, the samples in Comparative Example 4, of which silver powder was spherical particles (A) alone, exhibited a volume of resistivity larger than  $3\mu\Omega \bullet \text{cm}$ , resulting in poor conductivity.--**

*Please amend the paragraph on page 21 at line 10 as follows:*

--In the samples in Comparative Examples 4 to 6, which contained 5 wt% glass frit, cohesion failure occurred in the glass substrate even in the case of the film thickness being 15 $\mu$ m, thus allowing the coating thickness of 10  $\mu$ m or less.--